

# Bluetooth and MSP430™ Audio Reference Design Quick Start Guide

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## ABSTRACT

This document will help you quickly get started on CC256x Audio Sink demo and make this a smooth out-of-the-box experience.

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**NOTE:** This demo utilizes new audio features of the CC256xB dual mode Bluetooth controller, a new ROM spin of the CC256xA device. Apart from the device label, you can verify the correct part number by making sure the LMP subversion for CC256xB is 0x1B90 (instead of 0x1B0F for CC256xA) by issuing the HCI\_Read\_Local\_Version\_Information standard HCI command before loading the Service Pack.

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## 1 Out of the Box Demo

1. Plug in the USB cable to the USB connector (J4). Toggle switch 2 to the ON position to power up the board.

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**NOTE:** The board also has power options using alkaline batteries or rechargeable batteries.

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2. Make sure speakers are connected to J25. The recommended speaker can be purchased at <http://www.amazon.com/>, part number: B008BYXU72.
3. Go to the Bluetooth settings on the phone. Pair and connect to the device called "Headset" or "CC256x A3DP". If you are asked for the *passcode*, type in "0000". It should then say *Connected* under Bluetooth Devices.

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**NOTE:** If having trouble reconnecting after being previously paired to the device, try to disconnect and then reconnect.

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4. Play some songs and hear the music on the speakers streaming from the phone to the CC256x Sink board.

## 2 Software Update

The A3DP software can be downloaded from <http://www.ti.com/tool/stonestreetone-bt-sdk>.

To use the CC256XB module, the CC256XB.h patch has to be included.

"\_\_SUPPORT\_CC256XB\_PATCH\_\_" should already be defined in the preprocessor definitions. This will make sure that the CC256XB patch is loaded and the CC256XB module can be used without issues.

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